

What is claimed is:

1. A packaging structure for packaging a plurality of semiconductor chips, the packaging structure comprising a film on which the plurality of semiconductor chips are mounted, wherein the film is folded in a predetermined direction so as to package the plurality of semiconductor chips in one package.
2. The packaging structure as claimed in claim 1, wherein the film comprises:
an insulating film; and
a conductive pattern formed on the surface of the insulating film.
3. The packaging structure as claimed in claim 1, wherein the film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film.
4. The packaging structure as claimed in claim 1, wherein the package is a tape carrier package (TCP).
5. The packaging structure as claimed in claim 1, wherein the package is a chip-on-film (COF) package.
6. The packaging structure as claimed in claim 1, wherein the film is folded in a predetermined direction by 180° and is adhered by a predetermined adhesive material.
7. A method of packaging a device, comprising:
(a) mounting a plurality of semiconductor chips on a film; and
(b) folding the film in a predetermined direction and packaging the plurality of semiconductor chips in one package.

8. The method as claimed in claim 7, before step (a), further comprising:

forming an insulating film; and

forming a conductive pattern on the surface of the insulating film.

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9. The method as claimed in claim 7, wherein the film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film.

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10. The method as claimed in claim 7, wherein the film is folded by 180° and is adhered by an adhesive material.

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11. A package for two semiconductor chips, the package comprising a film on a first side of which the two semiconductor chips are mounted, wherein the film is folded by 180° in the direction of a second side so as to package the two semiconductor chips in one package.

12. The package as claimed in claim 11, wherein the film comprises:

an insulating film; and

a conductive pattern formed on the surface of the insulating film.

13. The package as claimed in claim 11, wherein the film is folded two or more times such that at least one semiconductor chip is interposed between surfaces of the film.

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14. The package as claimed in claim 11, wherein the package is a tape carrier package (TCP).

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15. The package as claimed in claim 11, wherein the package is a chip-on-film (COF) package.

16. The package as claimed in claim 11, wherein the film is folded in a predetermined direction by 180° and is adhered by a predetermined adhesive material.

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